

Date:- 15 Aug, 2002

Data Sheet Issue:- 1

Phase Control Thyristor Types N3012ZC200 to N3012ZC260

Old Type No.: N900CH20-26

Absolute Maximum Ratings

	VOLTAGE RATINGS	MAXIMUM LIMITS	UNITS
V_{DRM}	Repetitive peak off-state voltage, (note 1)	2000-2600	V
V_{DSM}	Non-repetitive peak off-state voltage, (note 1)	2000-2600	V
V_{RRM}	Repetitive peak reverse voltage, (note 1)	2000-2600	V
V_{RSM}	Non-repetitive peak reverse voltage, (note 1)	2100-2700	V

	OTHER RATINGS	MAXIMUM LIMITS	UNITS
I _{T(AV)M}	Maximum average on-state current, T _{sink} =55℃, (note 2)	3012	А
I _{T(AV)M}	Maximum average on-state current. T _{sink} =85℃, (note 2)	2084	Α
I _{T(AV)M}	Maximum average on-state current. T _{sink} =85℃, (note 3)	1275	Α
I _{T(RMS)}	Nominal RMS on-state current, T _{sink} =25℃, (note 2)	5922	Α
I _{T(d.c.)}	D.C. on-state current, T _{sink} =25℃, (note 4)	4056	Α
I _{TSM}	Peak non-repetitive surge t _p =10ms, V _{rm} =0.6V _{RRM} , (note 5)	45.1	kA
I _{TSM2}	Peak non-repetitive surge t _p =10ms, V _{rm} ≤10V, (note 5)	49.7	kA
l ² t	I^2 t capacity for fusing t_p =10ms, V_{rm} =0.6 V_{RRM} , (note 5)	10.2×10 ⁶	A ² s
l ² t	l ² t capacity for fusing t _p =10ms, V _{rm} ≤10V, (note 5)	12.4×10 ⁶	A ² s
(-1:/-14)	Critical rate of rise of on-state current (repetitive), (Note 6)	150	A/µs
(di/dt) _{cr}	Critical rate of rise of on-state current (non-repetitive), (Note 6)	300	A/µs
V_{RGM}	Peak reverse gate voltage	5	V
P _{G(AV)}	Mean forward gate power	5	W
P _{GM}	Peak forward gate power	30	W
T _{j op}	Operating temperature range	-40 to +125	C
T _{stg}	Storage temperature range	-40 to +150	C

Notes:-

- 1) De-rating factor of 0.13% per $\mathbb C$ is applicable for T_i below 25 $\mathbb C$.
- 2) Double side cooled, single phase; 50Hz, 180° half-sinewave.
- 3) Single side cooled, single phase; 50Hz, 180°half-sinewave.
- 4) Double side cooled.
- 5) Half-sinewave, 125℃ T_j initial.
- 6) $V_D=67\% \ V_{DRM}, \ I_{FG}=2A, \ t_r \le 0.5 \mu s, \ T_{case}=125 \ C.$



Characteristics

	PARAMETER	MIN.	TYP.	MAX.	TEST CONDITIONS (Note 1)	UNITS	
V_{TM}	Maximum peak on-state voltage	-	-	1.4	I _{TM} =3000A	V	
V_{T0}	Threshold voltage	-	-	0.92		V	
r⊤	Slope resistance	-	-	0.16		$m\Omega$	
(dv/dt) _{cr}	Critical rate of rise of off-state voltage	1000	-	-	V _D =80% V _{DRM} , linear ramp, gate o/c	V/μs	
I _{DRM}	Peak off-state current	-	-	200	Rated V _{DRM}	mA	
I _{RRM}	Peak reverse current	-	-	200	Rated V _{RRM}	mA	
V _{GT}	Gate trigger voltage	-	-	3.0	T 25%	V	
I _{GT}	Gate trigger current	-	-	300	$T_{j=25}$ °C $V_{D=10}V, I_{T=3}A$	mA	
V_{GD}	Gate non-trigger voltage	-	-	0.25	Rated V _{DRM}	V	
I _H	Holding current	-	-	1000	T _j =25℃	mA	
t _{gd}	Gate-controlled turn-on delay time		1.0	2.0	V _D =67% V _{DRM} , I _T =2000A, di/dt=10A/µs,	μs	
t _{gt}	Turn-on time	-	2.0	3.0	$I_{FG}=2A$, $t_r=0.5\mu s$, $T_j=25^{\circ}C$	μs	
Q _{rr}	Recovered charge	-	5300	-		μC	
Q_{ra}	Recovered charge, 50% Chord	-	3050	3600	I _{TM} =2000A, t _p =1000μs, di/dt=10A/μs,	μC	
I _{rm}	Reverse recovery current	-	175	-	V _r =50V	Α	
t _{rr}	Reverse recovery time	-	35	-		μs	
+	Turn-off time	-	300	-	I _{TM} =2000A, t _p =1000μs, di/dt=10A/μs, V _r =50V, V _{dr} =80%V _{DRM} , dV _{dr} /dt=20V/μs	110	
t _q	Turr-on une	-	600	-	I_{TM} =2000A, t_p =1000 μ s, di/dt =10A/ μ s, V_r =50V, V_{dr} =80% V_{DRM} , dV_{dr}/dt =200V/ μ s	μs	
D	Thermal registance, junction to be stainly	-	-	0.011	Double side cooled	K/W	
R_{thJK}	Thermal resistance, junction to heatsink	-	-	0.022	Single side cooled	K/W	
F	Mounting force	27	-	47		kN	
W_t	Weight	-	1.7	-		kg	

Notes:-

¹⁾ Unless otherwise indicated T_j=125°C.

Notes on Ratings and Characteristics

1.0 Voltage Grade Table

Voltage Grade	$V_{ m DRM} \ V_{ m DSM} \ V_{ m RRM} \ V$	V _{RSM} V	V _D V _R DC V
20	2000	2100	1250
22	2200	2300	1350
24	2400	2500	1450
26	2600	2700	1550

2.0 Extension of Voltage Grades

This report is applicable to other voltage grades when supply has been agreed by Sales/Production.

3.0 De-rating Factor

A blocking voltage de-rating factor of 0.13%/℃ is applicable to this device for T_i below 25℃.

4.0 Repetitive dv/dt

Standard dv/dt is 1000V/µs.

5.0 Snubber Components

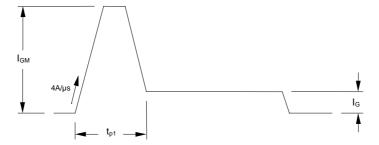
When selecting snubber components, care must be taken not to use excessively large values of snubber capacitor or excessively small values of snubber resistor. Such excessive component values may lead to device damage due to the large resultant values of snubber discharge current. If required, please consult the factory for assistance.

6.0 Rate of rise of on-state current

The maximum un-primed rate of rise of on-state current must not exceed 300A/µs at any time during turnon on a non-repetitive basis. For repetitive performance, the on-state rate of rise of current must not exceed 150A/µs at any time during turn-on. Note that these values of rate of rise of current apply to the total device current including that from any local snubber network.

7.0 Gate Drive

The nominal requirement for a typical gate drive is illustrated below. An open circuit voltage of at least 30V is assumed. This gate drive must be applied when using the full di/dt capability of the device.



The magnitude of I_{GM} should be between five and ten times I_{GT} , which is shown on page 2. Its duration (t_{p1}) should be 20µs or sufficient to allow the anode current to reach ten times I_L , whichever is greater. Otherwise, an increase in pulse current could be needed to supply the necessary charge to trigger. The 'back-porch' current I_G should remain flowing for the same duration as the anode current and have a magnitude in the order of 1.5 times I_{GT} .

8.0 Computer Modelling Parameters

8.1 Device Dissipation Calculations

8.1 Device Dissipation Calculations
$$I_{AV} = \frac{-V_{T0} + \sqrt{{V_{T0}}^2 + 4 \cdot ff \cdot r_T \cdot W_{AV}}}{2 \cdot ff \cdot r_T} \text{ and:} \qquad W_{AV} = \frac{\Delta T}{R_{th}} \\ \Delta T = T_{j \max} - T_{Hs}$$

Where V_{T0} =0.92V, r_T =0.16m Ω ,

 R_{th} = Supplementary thermal impedance, see table below and

ff = Form factor, see table below.

Supplementary Thermal Impedance							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave Double Side Cooled	0.0124	0.0122	0.0121	0.0119	0.0117	0.0113	0.011
Square wave Single Side Cooled	0.0249	0.0248	0.0247	0.0246	0.0244	0.0241	0.022
Sine wave Double Side Cooled	0.0168	0.0140	0.0131	0.0118	0.0112		
Sine wave Single Side Cooled	0.0249	0.0247	0.0246	0.0244	0.0241		

Form Factors							
Conduction Angle	30°	60°	90°	120°	180°	270°	d.c.
Square wave	3.464	2.449	2	1.732	1.414	1.149	1
Sine wave	3.98	2.778	2.22	1.879	1.57		

8.2 Calculating V_T using ABCD Coefficients

The on-state characteristic I_T vs. V_T , on page 6 is represented in two ways;

- the well established Vo and rs tangent used for rating purposes and
- a set of constants A, B, C, D, forming the coefficients of the representative equation for V_T in (ii) terms of I_T given below:

$$V_T = A + B \cdot \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

The constants, derived by curve fitting software, are given below for both hot and cold characteristics. The resulting values for V_T agree with the true device characteristic over a current range, which is limited to that plotted.

25℃ Coefficients			125℃ Coefficients
Α	0.498019438	Α	1.049896747
В	0.04122506	В	-0.0399690371
С	9.4563×10 ⁻⁵	С	5.2302×10 ⁻⁵
D	5.27375904×10 ⁻³	D	9.96560697×10 ⁻³

8.3 D.C. Thermal Impedance Calculation

$$r_{t} = \sum_{p=1}^{p=n} r_{p} \cdot \left(1 - e^{\frac{-t}{\tau_{p}}}\right)$$

Where p = 1 to n, n is the number of terms in the series and:

t = Duration of heating pulse in seconds.

 r_{t} = Thermal resistance at time t.

 r_p = Amplitude of p_{th} term.

 τ_p = Time Constant of r_{th} term.

The coefficients for this device are shown in the tables below:

D.C. Double Side Cooled							
Term	Term 1 2 3 4						
r_p	6.72×10 ⁻³	2.78×10 ⁻³	9.476×10 ⁻⁴	7.12×10 ⁻⁴			
$ au_{\!\scriptscriptstyle D}$	1.0226	0.226	0.0586	9.06×10 ⁻³			

D.C. Single Side Cooled						
Term 1 2 3 4						
r_p	0.01688	4.42×10 ⁻³	1.79×10 ⁻³	8.72×10 ⁻⁴		
$ au_{ ho}$	7.055	0.5206	0.1198	0.0128		

9.0 Reverse recovery ratings

(i) Q_{ra} is based on 50% I_{rm} chord as shown in Fig. 1

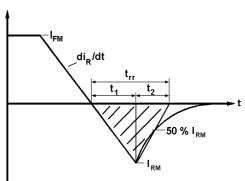


Fig. 1

(ii)
$$Q_{rr}$$
 is based on a 150 μ s integration time i.e.

$$Q_{rr} = \int_{0}^{150\,\mu s} i_{rm}.dt$$

(iii)
$$K Factor = \frac{t1}{t2}$$

Curves

Figure 1 - On-state characteristics of Limit device

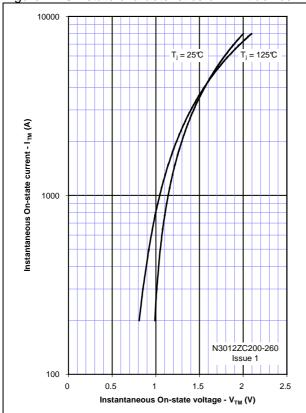


Figure 2 - Transient thermal impedance

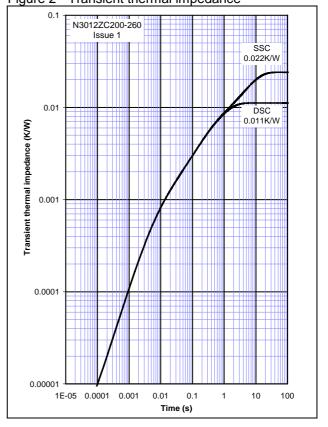


Figure 3 - Gate characteristics - Trigger limits

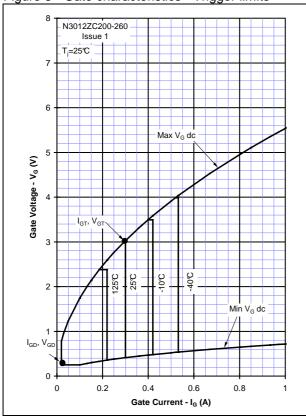
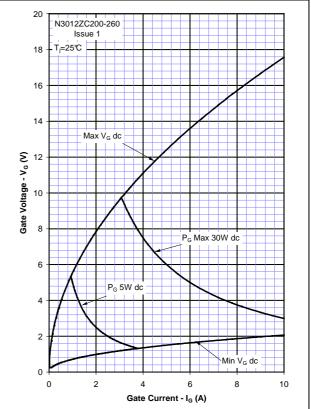


Figure 4 - Gate characteristics - Power curves



1000

Figure 5 - Total recovered charge, Q_{rr} 4000A 3000A 2000A Recovered charge - Q_{rr} (µC) 1000A 10000

10

T_j=125℃ N3012ZC200-260 Issue 1

1000

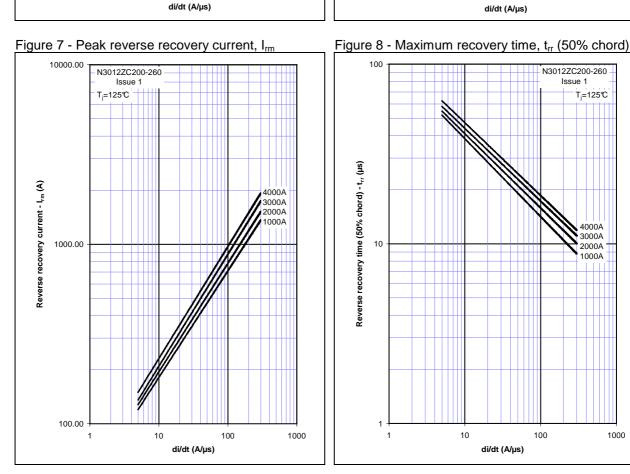
Figure 6 - Recovered charge, Q_{ra} (50% chord) N3012ZC200-260 Issue 1 3000A T_i=125℃ 2000A 1000A Recovered charge - Q_{ra}, 50% chord (µC) 1000

10

di/dt (A/µs)

100

1000



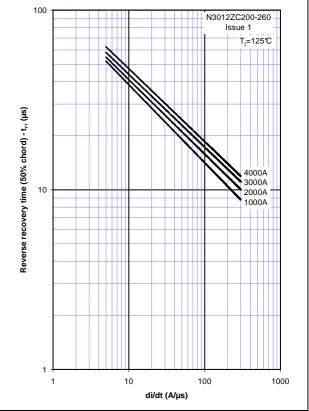


Figure 9 – On-state current vs. Power dissipation – Double Side Cooled (Sine wave)

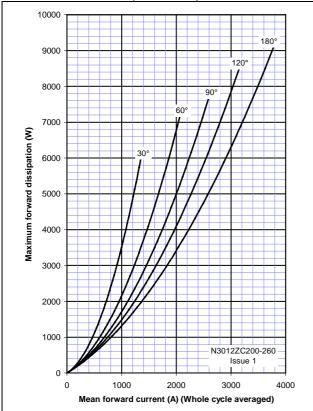


Figure 11 – On-state current vs. Power dissipation – Double Side Cooled (Square wave)

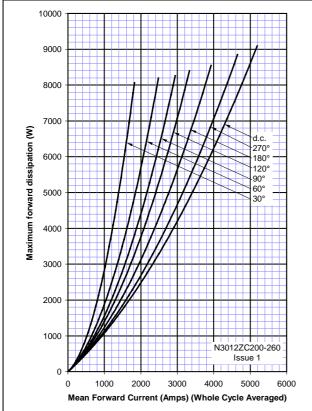


Figure 10 – On-state current vs. Heatsink temperature - Double Side Cooled (Sine wave)



Figure 12 – On-state current vs. Heatsink temperature – Double Side Cooled (Square wave)

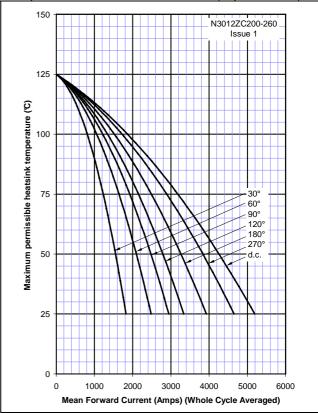


Figure 13 – On-state current vs. Power dissipation – Single Side Cooled (Sine wave)

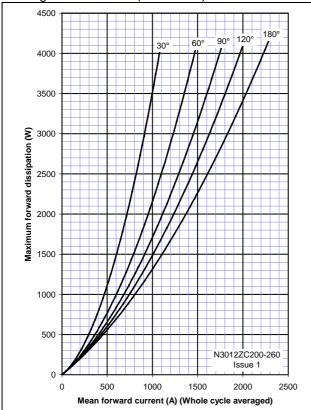


Figure 15 – On-state current vs. Power dissipation – Single Side Cooled (Square wave)

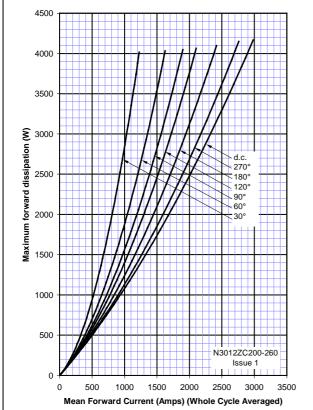


Figure 14 – On-state current vs. Heatsink temperature – Single Side Cooled (Sine wave)

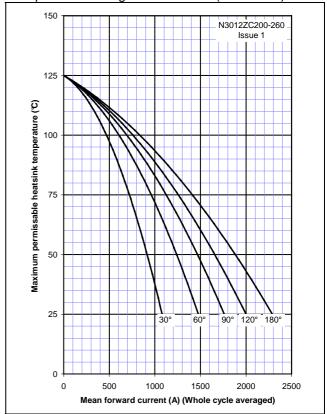
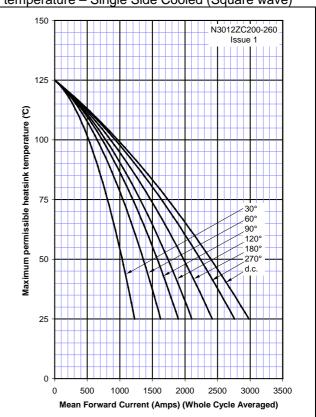
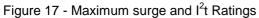
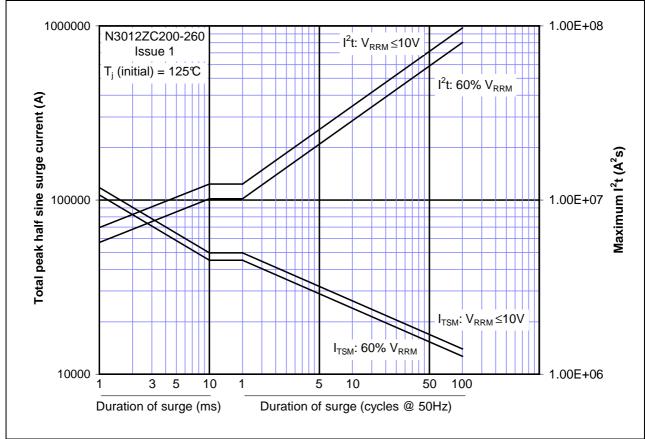


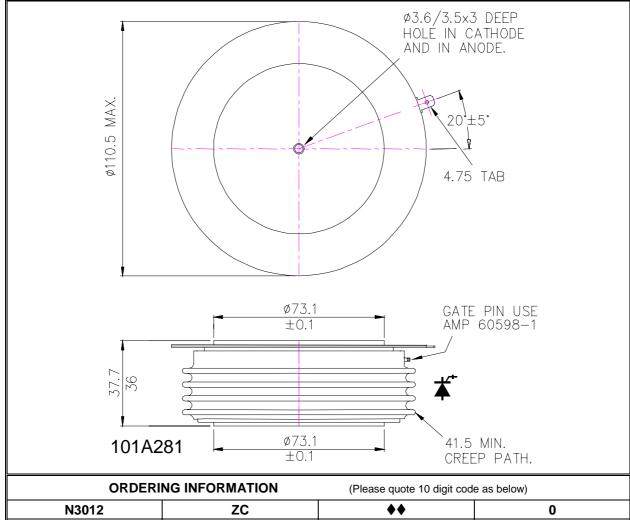
Figure 16 – On-state current vs. Heatsink temperature – Single Side Cooled (Square wave)







Outline Drawing & Ordering Information



N3012	ZC	**	0
Fixed Type Code	Fixed outline code	Voltage code V _{DRM} /100 20-26	Fixed turn-off time code

Order code: N3012ZC260 – 2600V V_{DRM}, V_{RRM}, 37.7mm clamp height capsule.

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